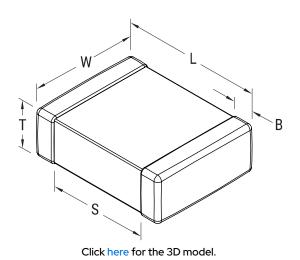


C0603C222K2GECTU

Aliases (C0603C222K2GEC7867)

ESD SMD Comm COG, Ceramic, 2,200 pF, 10%, 200 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0603, 0.5



General Information		
Series	ESD SMD Comm COG	
Style	SMD Chip	
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I	
Features	Temperature Stable, Low ESR, Class I	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	3.7 mg	
Shelf Life	78 Weeks	
MSL	1	

2,200 pF

1 kHz 1.0Vrms

0% Loss/Decade Hour

100 GOhms

Dimensions	
Chip Size	0603
L	1.6mm +/-0.15mm
W	0.8mm +/-0.15mm
Т	0.8mm +/-0.07mm
S	0.5mm MIN
В	0.35mm +/-0.15mm

W	0.8mm +/-0.15mm	Tolerance	10%
Т	0.8mm +/-0.07mm	Voltage DC	200 VDC
S	0.5mm MIN	ESD Level per AEC-Q200	12,000 V ESD Level
В	0.35mm +/-0.15mm	Dielectric Withstanding Voltage	500 VDC
		Temperature Range	-55/+125°C
Packaging Specifications		Temp. Coefficient	COG
Packaging	T&R, 180mm, Paper Tape	Capacitance Change with	30 ppm/C, 1kHz 1.0Vrms
Packaging Quantity	4000	Reference to +25°C and 0 VDC Applied (TCC)	., , ,
		Dissipation Factor	0.1% 1 kHz 1.0Vrms

Specifications

Measurement Condition

Capacitance

Aging Rate

Insulation Resistance

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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